

Docket No.: M4065.0394/P394
(PATENT)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:

Neo Chee Peng

Confirmation No.: 1491

Application No.: 09/805,111

Group Art Unit: 3724

Filed: March 14, 2001

Examiner: B. Ashley

For: IN-PROCESS TAPE BUR MONITORING

AMENDMENT

Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450 RECFIVED

JUL 0 9 2003

TECHNOLOGY CENTER R3700

Dear Sir:

In response to the Office Action dated April 25, 2003 (Paper No. 9), please amend the above-identified U.S. patent application as follows:

IN THE CLAIMS

Please cancel claim 3.

Please rewrite claims 1 and 7 as follows:

- 1. An cutting apparatus comprising:
 - a support for holding a wafer having a protective tape thereon;
- a cutting element placed at a first predetermined distance from said support for moving relative to said support to cut a portion of the protective tape from the wafer when the wafer is placed on the support;

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